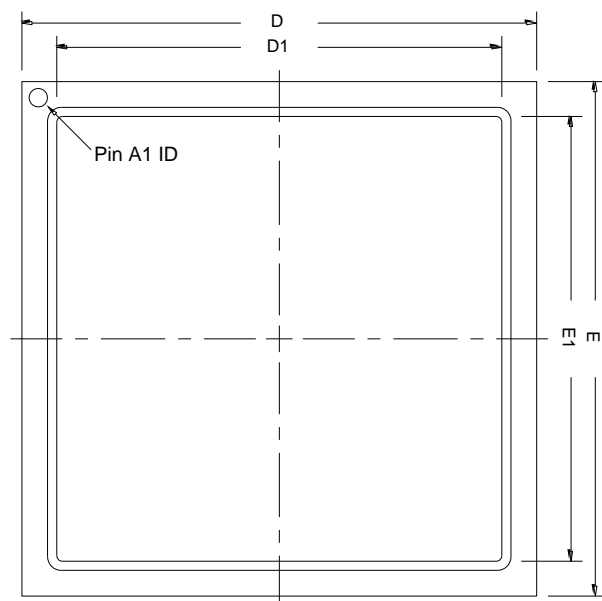
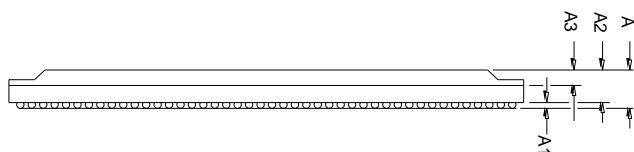
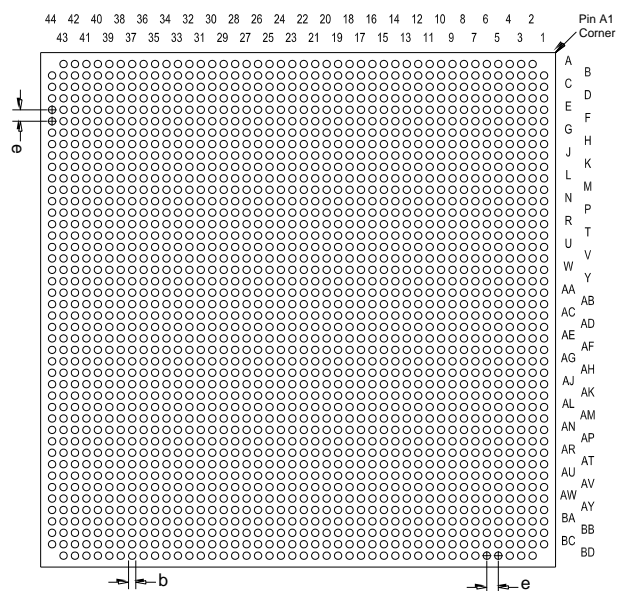


1932-Pin FineLine Ball-Grid Array (FBGA) - Flip Chip - Single-Piece Lid - A:3.60 - D1:38.9

- All dimensions and tolerances conform to ASME Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information	
Description	Specification
Ordering Code Reference	F
Package Acronym	FBGA
Substrate Material	BT
Solder ball composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)
JEDEC Outline Reference	MS-034 Variation: AAW-1
Lead Coplanarity	0.010 inch (0.25 mm)
Weight	20.0 g (Typ.)
Moisture Sensitivity Level	Printed on moisture barrier bag

Package Outline Dimension Table			
Symbol	Millimeters		
	Min.	Nom.	Max.
A	3.20	3.40	3.60
A1	0.40	0.50	0.60
A2	2.60	2.90	3.20
A3	1.30	1.40	1.50
D	45.00 BSC		
D1	38.90 BSC		
E	45.00 BSC		
E1	38.90 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		

Package Outline**TOP VIEW****BOTTOM VIEW**

Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
June 2011	1.0	Initial release



101 Innovation Drive
San Jose, CA 95134
www.altera.com

© 2011 Altera Corporation. All rights reserved. ALTERA, ARRIA, CYCLONE, HARDCOPY, MAX, MEGACORE, NIOS, QUARTUS and STRATIX are Reg. U.S. Pat. & Tm. Off. and/or trademarks of Altera Corporation in the U.S. and other countries. All other trademarks and service marks are the property of their respective holders as described at www.altera.com/common/legal.html. Altera warrants performance of its semiconductor products to current specifications in accordance with Altera's standard warranty, but reserves the right to make changes to any products and services at any time without notice. Altera assumes no responsibility or liability arising out of the application or use of any information, product, or service described herein except as expressly agreed to in writing by Altera. Altera customers are advised to obtain the latest version of device specifications before relying on any published information and before placing orders for products or services.